

	Type	Hits	Search Text	DBs
1	BRS	400	((silicon adj carbide) or sic) with ((silicon or si) adj (layer or film))	USPAT
2	BRS	33	((((silicon adj carbide) or sic) with ((silicon or si) adj (layer or film))) and barrier and (cu or copper)	USPAT
3	BRS	2518	((silicon adj carbide) or sic) and ((silicon or si) adj (layer or film))	USPAT
4	BRS	303	((((silicon adj carbide) or sic) and ((silicon or si) adj (layer or film))) and barrier and (cu or copper)	USPAT
5	BRS	1526	((silicon adj carbide) or sic) and ((silicon or si) adj (layer or film))	US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
6	BRS	115	((((silicon adj carbide) or sic) and ((silicon or si) adj (layer or film))) and barrier and (cu or copper)	US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
7	BRS	622	(sic or silicon adj carbide) with barrier	USPAT
8	IS&R	4029	(257/751,752,753,754,758,759,760,761,762,763,774).CCLS.	USPAT
9	BRS	176	((257/751,752,753,754,758,759,760,761,762,763,774).CCLS.) and (silicon adj carbide or sic)	USPAT
10	IS&R	4732	(438/622,626,627,628,629,631,633,643,653,648,649,644,656,687,719,753).CCLS.	USPAT
11	BRS	234	((438/622,626,627,628,629,631,633,643,653,648,649,644,656,687,719,753).CCLS.) and (silicon adj carbide or sic)	USPAT
12	BRS	30985	silicon near2 carbide	USPAT
13	BRS	40500	(silicon near2 carbide) or sic	USPAT
14	BRS	627	((silicon near2 carbide) or sic) with barrier	USPAT
15	BRS	160	((((silicon near2 carbide) or sic) with barrier) and interconnect\$4	USPAT
16	BRS	104	((((silicon near2 carbide) or sic) with barrier) and interconnect\$4) and (cu or copper)	USPAT
17	BRS	6362	porosity with (percent or percentage or "%")	USPAT
18	BRS	51	(porosity with (percent or percentage or "%")) with dielectric	USPAT
19	BRS	6496	porous with (percent or percentage or "%")	USPAT
20	BRS	79	(porous with (percent or percentage or "%")) with dielectric	USPAT
21	BRS	1145	(porous with (percent or percentage or "%")) with volume	USPAT
22	BRS	96	((porous with (percent or percentage or "%")) with volume) with interconnect\$4	USPAT

	Type	Hits	Search Text	DBs
23	BRS	25	((porous with (percent or percentage or "%")) with volume) and interconnect\$4 and semiconductor	USPAT
24	BRS	98	(porosity with (percent or percentage or "%")) and interconnect\$4 and semiconductor	USPAT
25	BRS	6	(porosity with (percent or percentage or "%")) and damascene	USPAT
26	BRS	6	(porous with (percent or percentage or "%")) and damascene	USPAT
27	BRS	81	porosity and damascene	USPAT
28	BRS	36	((((silicon adj carbide) or sic) with ((silicon or si) adj (layer or film))) and barrier and (cu or copper)	USPAT
29	BRS	349	((((silicon adj carbide) or sic) and ((silicon or si) adj (layer or film))) and barrier and (cu or copper)	USPAT
30	BRS	11	(sic silicon adj carbide) same ((trimethyl adj silane tms) and (helium he))	USPAT
31	BRS	13	(sic silicon adj carbide) same ((trimethyl adj silane tms) and (helium he))	US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
32	BRS	4	(sic silicon adj carbide) same ((trimethyl adj silane tms) and (helium he) and ammonia)	US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
33	BRS	301	((438/622,626,627,628,629,631,633,643,653,648, 649,644,656,687,719,753).CCLS.) and (silicon adj carbide or sic)	USPAT
34	BRS	209	((257/751,752,753,754,758,759,760,761,762,763, 774).CCLS.) and (silicon adj carbide or sic)	USPAT
35	BRS	38	((((silicon adj carbide) or sic) with ((silicon or si) adj (layer or film))) and barrier and (cu or copper)	USPAT
36	BRS	358	((((silicon adj carbide) or sic) and ((silicon or si) adj (layer or film))) and barrier and (cu or copper)	USPAT
37	BRS	6	("4865685"   "4948461"   "4981551"   "5436174"   "5571374"   "5818071").PN.	USPAT
38	BRS	317	((438/622,626,627,628,629,631,633,643,653,648, 649,644,656,687,719,753).CCLS.) and (silicon adj carbide or sic)	USPAT
39	BRS	216	((257/751,752,753,754,758,759,760,761,762,763, 774).CCLS.) and (silicon adj carbide or sic)	USPAT
40	BRS	454	((silicon adj carbide) or sic) with ((silicon or si) adj (layer or film))	USPAT
41	BRS	168	(((((silicon near2 carbide) or sic) with barrier) and interconnect\$4) and (cu or copper)	USPAT
42	BRS	226	((((silicon adj carbide) or sic) and ((silicon or si) adj (layer or film))) and barrier and (cu or copper)	US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
43	BRS	317	((438/622,626,627,628,629,631,633,643,653,648, 649,644,656,687,719,753).CCLS.) and (silicon adj carbide or sic)	USPAT

	Type	Hits	Search Text	DBs
44	BRS	169	((438/622,626,627,628,629,631,633,643,653,648,649,644,656,687,719,753).CCLS.) and (silicon adj carbide or sic)	US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
45	BRS	143	((257/751,752,753,754,758,759,760,761,762,763,774).CCLS.) and (silicon adj carbide or sic)	US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
46	BRS	50	((silicon adj carbide) or sic) with ((silicon or si) adj (layer or film))) and barrier and (cu or copper)	USPAT
47	BRS	444	((silicon adj carbide) or sic) and ((silicon or si) adj (layer or film))) and barrier and (cu or copper)	USPAT
48	BRS	433	((438/622,626,627,628,629,631,633,643,653,648,649,644,656,687,719,753).CCLS.) and (silicon adj carbide or sic)	USPAT
49	BRS	286	((257/751,752,753,754,758,759,760,761,762,763,774).CCLS.) and (silicon adj carbide or sic)	USPAT
50	BRS	522	((silicon adj carbide) or sic) with ((silicon or si) adj (layer or film))	USPAT
51	BRS	247	((silicon near2 carbide) or sic) with barrier) and interconnect\$4) and (cu or copper)	USPAT
52	BRS	433	((438/622,626,627,628,629,631,633,643,653,648,649,644,656,687,719,753).CCLS.) and (silicon adj carbide or sic)	USPAT
53	BRS	275	((438/622,626,627,628,629,631,633,643,653,648,649,644,656,687,719,753).CCLS.) and (silicon adj carbide or sic)	US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
54	BRS	240	((257/751,752,753,754,758,759,760,761,762,763,774).CCLS.) and (silicon adj carbide or sic)	US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
55	BRS	355	((silicon adj carbide) or sic) and ((silicon or si) adj (layer or film))) and barrier and (cu or copper)	US-PGPUB; EPO; JPO; DERWENT; IBM_TDB